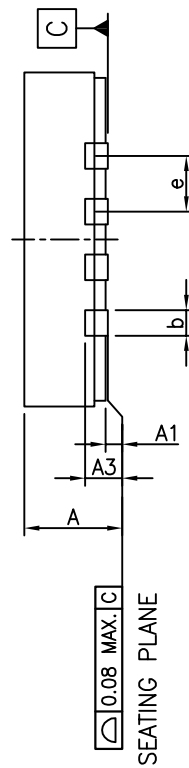
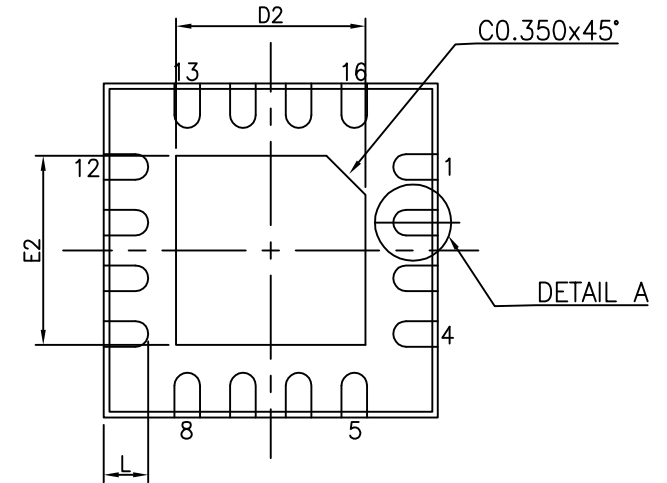


TOP VIEW

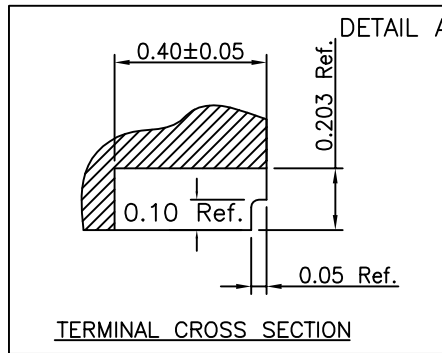


SEATING PLANE

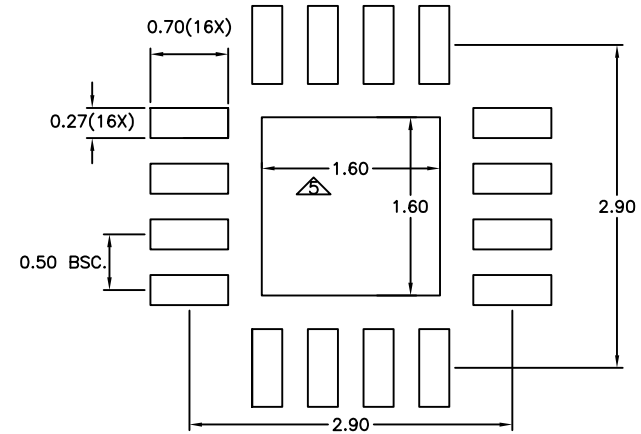


BOTTOM VIEW

SYMBOLS	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.203 REF.		
b	0.18	0.25	0.30
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.50 BSC		
K	0.20	—	—
D2	1.65	1.70	1.75
E2	1.65	1.70	1.75
L	0.35	0.40	0.45





TERMINAL CROSS SECTION



RECOMMENDED LAND PATTERN

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

		DATE: 03/17/17
	A PRODUCT LINE OF DIODES INCORPORATED ENABLING SERIAL CONNECTIVITY	
DESCRIPTION: 16-Contact, Very Thin Quad Flat No-Lead (TQFN)		
PACKAGE CODE: ZHQ (ZHQ16)		
DOCUMENT CONTROL #: PD-2225		REVISION: --